AMENDMENTS TO THE CLAIMS

This Listing of Claims will replace all prior Listings, and versions, of claims in the present application.

Listing of Claims:

 (Currently Amended) A biocompatible, human implantable apparatus, comprising:

a fully enclosed housing; and

a circuit encased within a brick of epoxy, wherein the brick of epoxy containing the circuit is housed in said housing; and

a second epoxy disposed between an outer surface of the brick of epoxy and an inner surface of the fully enclosed housing.

- (Original) The apparatus of claim 1, wherein the housing is a polymer housing and the polymer is an organic polymer.
- (Original) The apparatus of claim 2, wherein the polymer housing comprises

 PMMA.
- (Original) The apparatus of claim 2, wherein the polymer housing consists of PMMA.

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- (Original) The apparatus of claim 2, wherein the polymer housing consists essentially of PMMA.
- (Original) The apparatus of claim 1, wherein at least part of the circuit is covered with an epoxy including a light blocking pigment.
- (Original) The apparatus of claim 6, wherein the circuit comprises a substrate and a plurality of components attached to said substrate.
- 8. (Withdrawn) The apparatus of claim 1, further comprising a glass tube, wherein the epoxy brick containing the circuit is positioned within said glass tube and said glass tube is housed within said housing.
- (Withdrawn) The apparatus of claim 8, wherein a glass ball is used to seal an open end of said glass tube.
- (Withdrawn) The apparatus of claim 8, wherein an optical epoxy fills spaces between said glass tube and the inner wall of said housing.
- (Withdrawn) The apparatus of claim 8, wherein an optical epoxy fills spaces between said circuit and the inner wall of said glass tube.

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- (Original) The apparatus of claim 1, wherein the housing is substantially cylindrical in shape and has an inner diameter.
- 13. (Withdrawn) The apparatus of claim 12, wherein the inner diameter of the polymer housing is equal or about equal to the square root of: $(w^2 + h^2)$, where w is the width of the epoxy brick and h is the height of the epoxy brick.
- (Original) The apparatus of claim 1, wherein the housing does not comprise any glass.
 - (Withdrawn) A biocompatible, human implantable apparatus, comprising:
 a fully enclosed housing;
- a glass housing housed within said housing, the glass housing comprising a glass tube having an open end and a glass ball sealing said open end of said tube; and
 - a circuit housed within said glass housing.
- 16. (Withdrawn) The apparatus of claim 15, wherein the housing is a polymer housing and the polymer is an organic polymer.
- (Withdrawn) The apparatus of claim 16, wherein the polymer housing comprises

 PMMA.

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- (Withdrawn) The apparatus of claim 16, wherein the polymer housing consists of PMMA.
- (Withdrawn) The apparatus of claim 16, wherein the polymer housing consists essentially of PMMA.
- (Withdrawn) The apparatus of claim 15, wherein at least part of the circuit is covered with an epoxy including a light blocking pigment.
- (Withdrawn) The apparatus of claim 20, wherein the circuit comprises a substrate and a plurality of components attached to said substrate.
- 22. (Withdrawn) The apparatus of claim 15, further comprising optical epoxy, wherein the optical epoxy fills spaces between said glass housing and the inner wall of said housing.
- (Withdrawn) The apparatus of claim 15, wherein an optical epoxy fills spaces between said circuit and the inner wall of said glass housing.
- 24. (Withdrawn) A method for fully encasing a circuit within a polymer housing, comprising:

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placing the circuit in a mold;

injecting a formulation into the mold so that the formulation completely surrounds the circuit, wherein the formulation comprises monomers; and

polymerizing the monomers.

- 25. (Withdrawn) The method of claim 24, further comprising the step of covering the circuit with an epoxy prior to placing the circuit in the mold, wherein a sufficient amount of epoxy is used to cover the circuit so that the resulting surface topology is substantially smooth.
- 26. (Withdrawn) The method of claim 24, wherein the polymerization step is performed in a pressure vessel where the pressure is increased to at least about 125 psi using inert gas.
- (Withdrawn) The method of claim 24, wherein the formulation comprises MMA monomers.
- (Withdrawn) The method of claim 27, wherein the formulation further comprises pre-polymerized PMMA.
- (Withdrawn) The method of claim 28, wherein the formulation comprises between 60% and 80% pre-polymerized PMMA by volume.
- (Withdrawn) The method of claim 24, wherein the formulation consists essentially of MMA monomers.

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- (Withdrawn) The method of claim 24, wherein the formulation consists of MMA monomers.
 - (Withdrawn) A method for fully encasing a circuit within a housing, comprising: inserting the circuit into the housing;

injecting an optical epoxy into the housing;

placing the housing containing the optical epoxy and the circuit into a pressure vessel;

increasing the pressure within the vessel;

increasing the temperature within the vessel;

allowing the optical epoxy to cure;

removing the housing from the pressure vessel; and

capping an open end of the housing.

- 33. (Withdrawn) The method of claim 32, wherein the housing comprises PMMA.
- (Withdrawn) The method of claim 32, wherein the housing consists essentially of PMMA.
- 35. (Withdrawn) The method of claim 32, further comprising the step of encasing the circuit within an epoxy brick prior to placing the circuit in the housing.

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- (Withdrawn) The method of claim 32, wherein the pressure is increased to at least about 125 psi.
- (Withdrawn) The method of claim 32, wherein the temperature is increased to about 40 degrees centigrade.
- 38. (Withdrawn) The method of claim 32, wherein the circuit is inserted into the housing after the optical epoxy is injected into the housing.
- (Withdrawn) The method of claim 32, wherein the circuit is inserted into the housing before the optical epoxy is injected into the housing.
 - 40. (Withdrawn) A method for fully encasing a circuit within a housing, comprising: inserting the circuit into the glass housing; injecting an optical epoxy into a glass housing; injecting an optical epoxy into a second housing; inserting into the second housing the glass housing containing the circuit; capping an open end of the glass housing; and capping an open end of the second housing.
- (Withdrawn) The method of claim 40, wherein the second housing comprises

 PMMA.

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 (Withdrawn) The method of claim 40, wherein the second housing consists essentially of PMMA.

- 43. (Withdrawn) The method of claim 40, further comprising the step of encasing the circuit within an epoxy brick prior to placing the circuit in the glass housing.
- 44. (Withdrawn) The method of claim 40, wherein the circuit is inserted into the glass housing after the optical epoxy is injected into the glass housing.
- 45. (Withdrawn) The method of claim 40, wherein the circuit is inserted into the glass housing before the optical epoxy is injected into the glass housing.
- 46. (Withdrawn) The method of claim 40, wherein the step of capping an open end of the glass housing comprises the step of inserting a glass ball at least partially into said open end of the glass housing.
- 47. (Withdrawn) The method of claim 40, further comprising the step of curing the optical epoxy contained in the glass housing prior to inserting the glass housing into the second housing.
- 48. (Withdrawn) The method of claim 47, wherein the step of curing the optical epoxy comprises the step of placing the glass housing containing the optical epoxy and the circuit into a pressure vessel and increasing the temperature and pressure within the vessel.

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- 49. (Withdrawn) The method of claim 40, further comprising the step of curing the optical epoxy contained in the glass housing after inserting the glass housing into the second housing.
 - 50. (New) A biocompatible, human implantable apparatus, comprising:
 - a fully enclosed housing; and
- a circuit encased within a brick of epoxy, wherein the brick of epoxy is comprised of a polymerized formulation of monomers and polymers, and said brick of epoxy containing the circuit is housed in said housing.